

HYBOND

Soft Touch™

MODEL 572A

DEEP ACCESS THERMOSONIC WIRE AND RIBBON BONDER

0.5 to 2.0 mil (12.7 to 50um) diameter wire and up to 1 x 10 mil (25.4 x 254um) ribbon



STANDARD FEATURES:

- HYBOND *Soft Touch* energy system.
- Front panel ultrasonic test button.
- Deep vertical access of 0.59 in. (1,49cm).
- Long horizontal reach of 3.5 in. (8,89cm).
- 0.5 inch and 2 inch spool mounts standard.
- Loop height control adjustment.
- Motorized vertical wire feed.
- 1-1-2; 1-2-2 and 1-2-1 stitch capability.
- Swing away clamps for easier wire threading.
- Deep access wire-in-tool 90° wire feed.
- Variable angle microscope mount.
- Audio and visual bond fault indicators.
- Independent 1st and 2nd bond controls.
- Front panel feed switch for manual tail adjust.
- 6 x 8.5 in. (15,24cm x 21,59) X-Y work platform.
- LED display for monitoring temperature.
- Independent lever for Z bond head control.
- Wire and ribbon bonding capability.

Imitated but never duplicated, HYBOND's exclusive *Soft Touch™* force ramping system bonds effectively with less trauma to sensitive materials like GaAs and InP in FETs and MMICs. Superior wire control is provided by the motorized feed system which features clamps capable of feeding wire and ribbon, dial adjustable tail length, switch for manual tail length adjustment and clamp pull back dial adjustment to allow bonding and cutting of softer (higher elongation) wires than conventionally used for wedge bonding. Model 572A includes front panel independent controls for 1st and 2nd bond U/S, Time & Force as well as for the built in work stage temperature controller. The 572A has a proven track record of safe and effective wire and ribbon bonding worldwide.

Partial List of Available Options:

- **OP-06B:** Nikon SMZ745 Stereo Microscope.
- **CCTV-XX:** Microscope, Camera, Monitor, etc.
- **OP-08A-LED:** Dual Fiber Optic Illuminator.
- **OP-08R1-LED:** White LED Ring Illuminator.
- **OP-12:** 240VAC 50/60Hz Input Wiring.
- **OP-17:** Motorized de-spooler.
- **OP-30:** 8:1 X-Y Manipulator (4:1 Standard).
- **OP-31:** Tool Heater and Temp. Controller.
- **OP-47:** Beam Lead/Die Pick, Place & Bond.
- **OP-83:** Heated Transducer for Tool Heat.
- **WST-15A:** Heated Work Stage, 2.125in top.
- **WST-15B:** Heated Work Stage, 3.3in top.
- **WST-15CM:** Heated Work Stage, rotating top.
- **Wire & Wedge Tool** as ordered per application.

Specifications for Model 572A:

- Ultrasonic (U/S) System: PLL self tuning 62.5KHz (nominal) system (± 2.5 KHz).
- U/S Power Range: 0-1 watt on low setting (default) and 0-2 watts on high setting.
- Bond Time Range: 10mSec. to 400mSec.
- Bond Force Range: 15gr. to 150gr.
- Temperature Control Range: Ambient to 250 degrees Celsius.
- Bondable Wire Diameters: 0.5 to 2.0mil (12,7 to 50 μ m) diameter.
- Bondable Ribbon Dimensions: Up to 1 x 10mil (25,4 x 254 μ m).
- Bondable Wire/Ribbon Materials: Gold, aluminum, platinum, copper, silver.
- Bond Head Movement: Manual.
- Bond Actuation: Switch at fixed height. Activated by lever.
- Z Travel/Vertical Bonding Window: 0.5in. (12,7mm)/60-100mils (1,52-2,54 mm).
- Table Motion: 4:1, manual manipulator standard.
- Input Power Requirements: 110VAC 50/60Hz @ 10A max. or 240VAC with OP-12.
- Minimum Bench Space Required: Width: 20in., Depth: 20in. (50,8 x 50,8cm).
- Unit Weight/Shipping Weight: 55 lbs. (24,9Kg)/135 lbs. (61,4Kg). Shipping weight may vary.
- Vacuum Requirement: Vacuum = 20 inHg minimum.
- Industry Standards: CE.

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